



# Product Change Notification

## 113832 - 00

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# Product Change Notification

**Change Notification #:** 113832 - 00  
**Change Title:** Intel® Spare Board F2U12X35HSBP and FXX8X25HSBP  
PCN 113832-00, Product Design  
Update the ply stackup of the Printed Circuit Board  
**Date of Publication:** May 5, 2015

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material *:</b>	May 20, 2015
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*\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

## Description of Change to the Customer:

Intel is implementing the following change on the Intel® Spare Board F2U12X35HSBP and FXX8X25HSBP:

- Update the ply stackup of the Printed Circuit Board from single-layer to double-layer.

## Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change. Customers may need to validate the function and feature changes once the post-change spare board is available.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA	Pre Change PBA	Post Change PBA
F2U12X35HSBP	917976	G49869-001	G49869-002	G43212-250	G43212-350
FXX8X25HSBP	917973	G49866-001	G49866-002	G15232-451	G15232-550

## PCN Revision History:

<b>Date of Revision:</b>	<b>Revision Number:</b>	<b>Reason:</b>
May 5, 2015	00	Originally Published PCN